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- **Members of the Texas Instruments** Widebus™ Family
- Output Ports Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center **Spacings**

description

The 'ABT162825 are 18-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices provide true data, and can be used as two 9-bit buffers or one 18-bit buffer.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all nine affected outputs are in the high-impedance state.

SN54ABT162825 . . . WD PACKAGE SN74ABT162825...DL PACKAGE (TOP VIEW)

1 0E1 [$ _{1}$	56	10E2
1Y1 []1A1
1Y2[3	54] 1A2
GND[4		GND
1Y3[5	52] 1A3
1Y4 [6	51] 1A4
V _{CC} [7	50]v _{cc}
1Y5 [8] 1A5
1Y6	9	48] 1A6
1Y7 [10] 1A7
GND [11		GND
1Y8 [] 1A8
1Y9[13	44] 1A9
GND [14	43	GND
GND [15		GND
2Y1 [16	41] 2A1
2Y2[17]2A2
GND [GND
2Y3[19] 2A3
2Y4 [20	37] 2A4
2Y5 [21	36	2A5
V _{CC} [35	
2Y6[34] 2A6
2Y7 [33	P =:
GND [GND
2Y8	26	31	2A8
2Y9	1	30	2 <u>A9</u>
2 <mark>0E1</mark> [28	29	2 <mark>0E2</mark>
			•

The outputs, which are designed to source or sink up to 12 mA, include equivalent $25-\Omega$ series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT162825 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT162825 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

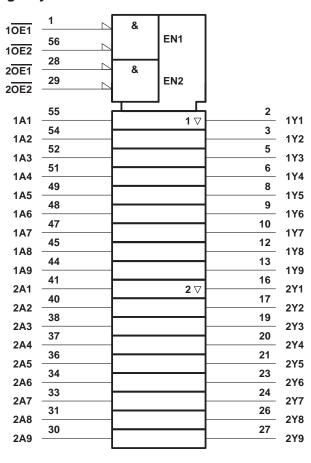
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FUNCTION TABLE (each 9-bit buffer)

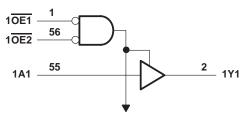
	INPUTS	OUTPUT			
OE1	OE2	Α	Υ		
L	L	L	L		
L	L	Н	Н		
Н	X	Χ	Z		
Х	Н	Χ	Z		

logic symbol†

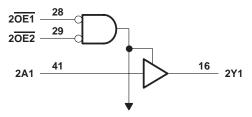


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Eight Other Channels



To Eight Other Channels

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, I _O	30 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT162825		SN74ABT162825		UNIT
			MIN	MAX	MIN	MAX	UNII
VCC	V _{CC} Supply voltage				4.5	5.5	V
VIH	H High-level input voltage				2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage			VCC	0	VCC	V
IOH	High-level output current			-12		-12	mA
loL	OL Low-level output current			12		12	mA
Δt/Δν	Input transition rise or fall rate	Control inputs	90	9		9	ns/V
ΔΨΔν	input transition rise of fail fate	Data inputs	Q	10		10	115/ V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature	_	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT162825		SN74ABT162825		UNIT	
				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.5			2.5		2.5		V	
\ \/a		$V_{CC} = 5 V$,	$I_{OH} = -1 \text{ mA}$	3			3		3			
VOH		V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4			2.4		2.4		V	
		VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2			2		2			
VOL		V _{CC} = 4.5 V	I _{OL} = 8 mA		0.4	0.8		0.8		0.65	V	
VOL		VCC = 4.5 V	I _{OL} = 12 mA							8.0	V	
V _{hys}					100						mV	
lj		$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ	
lozpu [‡]	:	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7$	V, $\overline{OE} = X$			±50		±50		±50	μА	
lozpd [‡]	:	$V_{CC} = 2.1 \text{ V to } 0,$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{OE} = X$				±50		±50		±50	μА	
I _{OZH} §	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$				10	Š	10		10	μА		
$V_{CC} = 2$ $V_{O} = 0.5$		$V_{CC} = 2.1 \text{ V to } 5.$ $V_{O} = 0.5 \text{ V}, \overline{\text{OE}} \ge$	5 V, 2 V			-10	DUC;	-10		-10	μΑ	
loff		$V_{CC} = 0$,	V _I or V _O ≤ 4.5 V			±100	Ø.			±100	μΑ	
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	V _O = 5.5 V			50	7	50		50	μΑ	
IOI		V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-75	-100	-25	-100	-25	-100	mA	
	Outputs high				•	2		2		2		
Icc	Outputs low	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$				32		32		32	mA.	
100	Outputs disabled	V _I = V _{CC} or GND				2		2		2	ША	
	Data inputs	V _{CC} = 5.5 V, One input at	Outputs enabled			1		1.5		1		
∆lCC#	Data IIIputs	Ot	3.4 V, Other inputs at V _{CC} or GND	Outputs disabled			0.05		1		0.05	mA
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5		
Ci		V _I = 2.5 V or 0.5 V			3.5						pF	
Co		V _O = 2.5 V or 0.5 V			8						pF	

 $[\]frac{1}{1}$ All typical values are at $V_{CC} = 5$ V.

[‡] This parameter is characterized, but not production tested.

[§] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

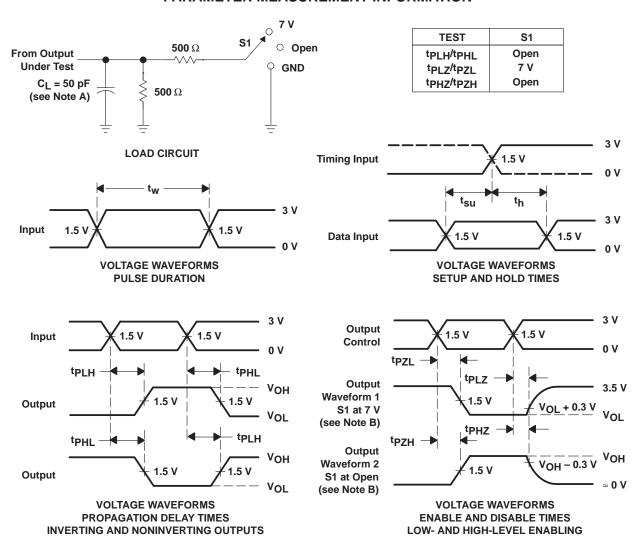
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT162825		SN74ABT162825		UNIT
	(INFO1)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	· ·	1	2.1	3.6	1	4.1	1	3.9	ns
^t PHL	A	T	1.1	2.8	4.2	1.1	5	1.1	4.7	115
^t PZH	ŌĒ	OE Y	1.5	3.4	6.3	1.5	7.2	1.5	6.9	ns
t _{PZL}			1.6	3.5	7.3	1.6	6.6	1.6	6.3	115
^t PHZ	ŌĒ	V	2.1	4.1	6.5	2.1	6.8	2.1	6.6	no
tPLZ		T	1.5	3.5	5.9	1.5	7.3	1.5	6.3	ns

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_{\Gamma} \leq$ 2.5 ns, $t_{\Gamma} \leq$ 2.5 ns,
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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